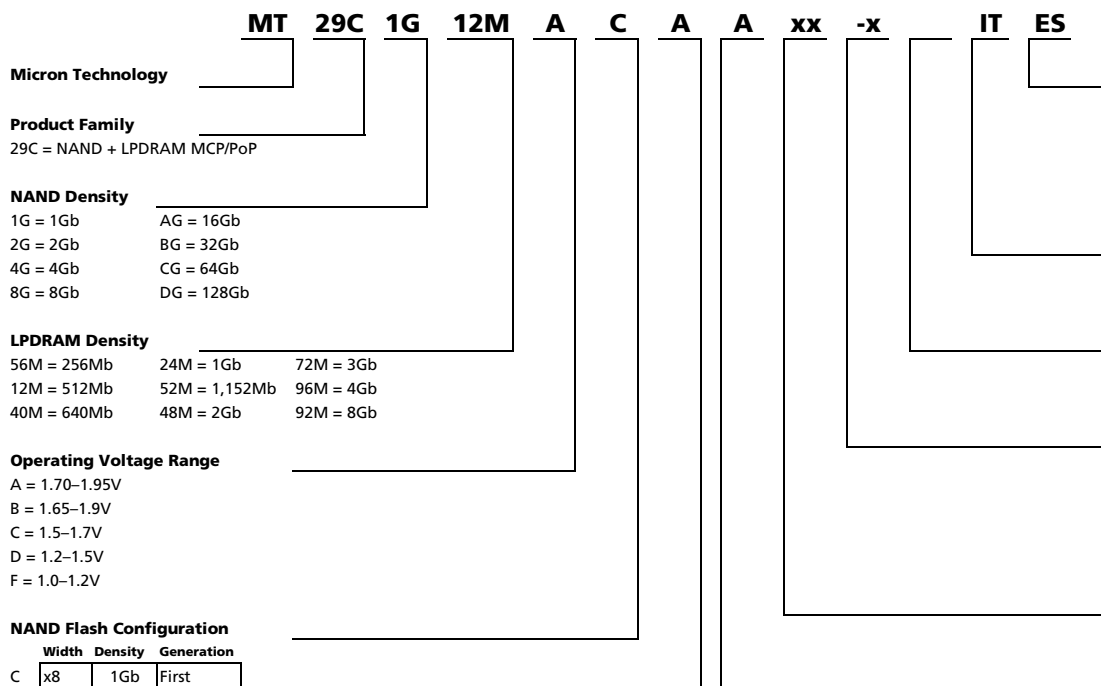


# MCP/PoP Part Numbering System

Micron's part numbering system is available at [www.micron.com/numbering](http://www.micron.com/numbering)

## Multichip Packages



### Micron Technology

### Product Family

29C = NAND + LPDRAM MCP/PoP

### NAND Density

1G = 1Gb  
2G = 2Gb  
4G = 4Gb  
8G = 8Gb

AG = 16Gb  
BG = 32Gb  
CG = 64Gb  
DG = 128Gb

### LPDRAM Density

56M = 256Mb  
12M = 512Mb  
40M = 640Mb

24M = 1Gb  
52M = 1,152Mb  
48M = 2Gb

72M = 3Gb  
96M = 4Gb  
92M = 8Gb

### Operating Voltage Range

A = 1.70-1.95V  
B = 1.65-1.9V  
C = 1.5-1.7V  
D = 1.2-1.5V  
F = 1.0-1.2V

### NAND Flash Configuration

	Width	Density	Generation
C	x8	1Gb	First
D	x16	1Gb	First
J	x8	2Gb	Second
K	x16	2Gb	Second
N	x8	4Gb	First
P	x16	4Gb	First
U	x8	1Gb	Second
V	x16	1Gb	Second
Y	x8	4Gb	Second
Z	x16	4Gb	Second
AA	x8	2Gb	Third
AB	x16	2Gb	Third
AC	x8	1Gb	Third
AD	x16	1Gb	Third
AE	x8	8Gb	First
AF	x16	8Gb	First
AG	x8	4Gb	Fourth
AH	x16	4Gb	Fourth
AI	x8	1Gb	Fourth
AJ	x16	1Gb	Fourth

### LPDRAM Configuration

	Type	Width	Density	Generation
A	DDR	x16	512Mb	First
C	DDR	x32	512Mb	First
J	DDR	x16	1Gb	First
L	DDR	x32	1Gb	First
N	DDR	x16	512Mb	Second
P	SDR	x16	512Mb	Second
R	DDR	x32	512Mb	Second
T	SDR	x32	512Mb	Second
V	DDR	x16	512Mb	Third
Y	DDR	x32	512Mb	Third
Z	SDR	x16	256Mb	First
AA	DDR	x16	256Mb	First
AE	SDR	x16	512Mb	Third
AF	SDR	x32	512Mb	Third
AG	SDR	x16 + x16	512Mb + 128Mb	First
AH	DDR	x16	1Gb	Second
AJ	SDR	x16	1Gb	First
AK	DDR	x32	1Gb	Second
AL	SDR	x32	1Gb	First
AM	DDR	x16	2Gb	First
AN	SDR	x16	2Gb	First
AP	DDR	x32	2Gb	First
AR	SDR	x32	2Gb	First
AS	SDR	x16 (2) + x16	1Gb + 128Mb	First
AT	DDR	x16 (2) + x32	2Gb + 1Gb	First
AU	DDR	x32	256Mb	First
AV	SDR	x32	256Mb	First
AY	DDR	x32 (x2)	4Gb + 1Gb	First/Second
AZ	DDR	x16	2Gb	Second
BA	DDR	x32	2Gb	Second

### Production Status

Blank = Production  
ES = Engineering samples  
DC = Daisy chain  
QS = Qualification samples  
MS = Mechanical samples

### Operating Temperature Range

IT = Industrial (-40°C to +85°C)  
WT = Wireless (-25°C to +85°C)

### Special Options

Blank = Standard  
E = On-die ECC enabled

### LPDRAM Access Time

-5 = 200 MHz CL3  
-54 = 185 MHz CL3  
-6 = 166 MHz CL3  
-75 = 135 MHz CL3  
-8 = 125 MHz CL3

### Package Code

Contact factory

### Chip Count

	CE#	Chip Count
A	1, 1	1 NAND, 1 LPDRAM
B	2, 1	2 NAND, 1 LPDRAM
C	1, 2	1 NAND, 2 LPDRAM
D	2, 2	2 NAND, 2 LPDRAM
E	1, 2	1 NAND, 3 LPDRAM
F	1, 2	2 NAND, 3 LPDRAM
G	1, 2	1 NAND, 4 LPDRAM
H	1, 3	1 NAND, 3 LPDRAM